

Initial Product/Process Change Notification

Document #:IPCN23890X Issue Date:23 Feb 2021

| Title of Change: | WDFN10 Wire convers | WDFN10 Wire conversion from Gold wire to Palladium coated copper wire. | | |
|---|---|--|--|--|
| Proposed First Ship date: | 30 Jun 2021 or earlier if approved by customer | | | |
| Contact Information: | Contact your local ON Semiconductor Sales Office or BernardRajVellangani.Pelevindran@onsemi.com | | | |
| PCN Samples Contact: | Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com >. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. | | | |
| Type of Notification: | advance notification al change details and dev The completed qualific Product/Process Chang Product/Process Chang | This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com > | | |
| Marking of Parts/ Traceability of Change: | Will carry date code m | Will carry date code marking "PZ" W21'2021 and above. | | |
| Change Category: | Assembly Change | Assembly Change | | |
| Change Sub-Category(s): | Material Change | Material Change | | |
| Sites Affected: | | | | |
| ON Semiconductor Sites | | External Foundry/Subcon Sites | | |
| ON Semiconductor Seremban, Malaysia | | None | | |
| | | • | | |

Description and Purpose:

| | Before Change Description | After Change Description | |
|-----------|---------------------------|-------------------------------------|--|
| Bond Wire | 2.0mil Gold wire | 2.0mil Palladium Coated Copper Wire | |

There is no product marking change as a result of this change.

Qualification Plan:

QV1 DEVICE NAME: <u>NIS5021MT2TXG</u> **PACKAGE:** <u>WDFN10 4.0*4.0*.75MM</u>

| Test | Specification | Condition | Interval |
|-----------|-------------------------|---|-----------|
| HTOL | TA=125C JA108 | TA=125C, bias at 1.2X Nominal (not to exceed Max rate | 1008 hrs |
| HTRB | JESD22-A108 | Tj = Max rate Tj for device, bias = 100% of rated V for Q 101 Rev D | 1008 hrs |
| HTSL | JESD22-A103 | Ta =Max rate storage temp for device | 2016 hrs |
| PC | J STD 020 , JESD22-A113 | IR reflow at 260C | |
| HAST+PC | JESD22-A110 | Temp = 130C, 85% RH, ~ 18.8 psig, bias = 100% of rated V or 100V max | 192 hours |
| TC+PC | JESD22-A104 | Temp = -65° C to $+150^{\circ}$ C; for 1000 cycles (or equivalent) | 1000 cyc |
| UHAST+ PC | JESD22-A118 | Temp = 130C, RH=85%, ~ 18.8 psig | 96 hrs |
| RSH | JESD22-B106 | Ta=265C 10 sec dwell B106 | |

Estimated date for qualification completion: 31 May 2021

TEM001790 Rev. D Page 1 of 2



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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

| Part Number | Qualification Vehicle |
|---------------|-----------------------|
| NIS5021MT1TXG | NIS5021MT2TXG |
| NIS5020MT1TXG | NIS5021MT2TXG |
| NIS5020MT2TXG | NIS5021MT2TXG |
| NIS5820MT1TXG | NIS5021MT2TXG |
| NIS5820MT2TXG | NIS5021MT2TXG |
| NIS5021MT2TXG | NA |

TEM001790 Rev. D Page 2 of 2